

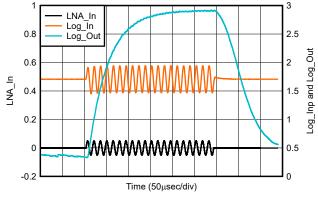
LOG300 40MHz, Logarithmic Detector With Integrated Low-Noise Amplifier

1 Features

- Input range:
 - LNA + log detector: 6µV_P to 200mV_P
 - Log detector: 20µV_P to 1.6V_P
- Low input-referred noise: $< 3\mu V_{RMS}$
- Dynamic range: 98dB with log conformance error $(LCE) = \pm 1.2dB$
- Signal detection up to 40MHz; even higher with reduced LCE
- Input frequency detection, zero cross detect
- Supply: 3V to 5.25V

2 Applications

- Ultrasonic distance and material sensing
- Flow cytometry
- ESD and high energy EMI signal detection
- **Energy detection**
- Bubble, occlusion detection



3 Description

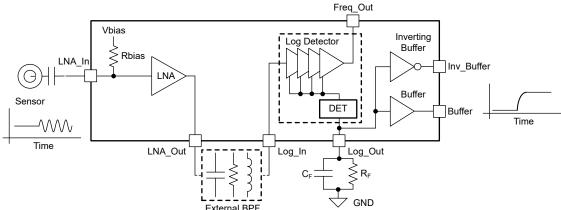
The LOG300 is an integrated Analog Front End (AFE) consisting of low-noise amplifier (LNA) and a Log Detector block. This device supports an input frequency range of up-to 40MHz and a typical dynamic range of 98dB. The LOG300 is intended for use in applications that require a wide dynamic range of voltage and signal measurement. The Log Detector block of LOG300 supports both single-ended and differential inputs. The low input noise of the integrated LNA, allows measurement of signals as low as $6\mu V_P$. The transient output response can be adjusted by tuning the capacitor connected at the Log Out pin. The integrated frequency detect feature of LOG300 enables users to extract input signal frequency and zero-crossing information.

The LOG300 is available in a 16-pin SOIC and 16-pin VQFN package. The LOG300 is operational from a 3V to 5.25V supply and over the full ambient temperature range of -40°C to +125°C.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
LOG300	D (SOIC, 16)	9.9mm × 6mm
	RGT (VQFN, 16)	3mm × 3mm

- For more information, see Section 11.
- The package size (length × width) is a nominal value and includes pins, where applicable.



Logarithmic Detector / Envelope Detector



Table of Contents

1 Features1	7.2 Functional Block Diagram17
2 Applications1	7.3 Feature Description17
3 Description1	7.4 Device Functional Modes19
4 Pin Configuration and Functions3	8 Application and Implementation20
5 Specifications4	8.1 Application Information
5.1 Absolute Maximum Ratings4	8.2 Typical Application20
5.2 ESD Ratings4	8.3 Power Supply Recommendations22
5.3 Recommended Operating Conditions4	8.4 Layout23
5.4 Thermal Information4	9 Device and Documentation Support24
5.5 Electrical Characteristics Low Noise Amplifier	9.1 Third-Party Products Disclaimer24
(LNA)5	9.2 Receiving Notification of Documentation Updates24
5.6 Electrical Characteristics Log Detector6	9.3 Support Resources24
5.7 Electrical Characteristics LNA + Log Detector	9.4 Trademarks24
(AFE)8	9.5 Electrostatic Discharge Caution24
5.8 Typical Characteristics: VCC = 5V9	9.6 Glossary24
5.9 Typical Characteristics: VCC = 3.3V15	10 Revision History24
6 Parameter Measurement Information16	11 Mechanical, Packaging, and Orderable
7 Detailed Description17	Information24
7.1 Overview17	



4 Pin Configuration and Functions

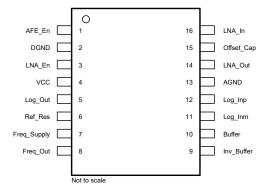


Figure 4-1. D Package, 16-Pin SOIC (top view)

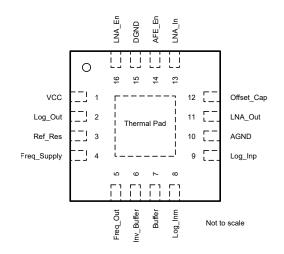


Figure 4-2. RGT Package, 16-Pin VQFN (top view)

Table 4-1. Pin Functions

PIN				Mic 4-1.1 III T unctions
		10.	TYPE(1)	DESCRIPTION
D (SOIC) RGT (VQF		RGT (VQFN)	-	
AFE_En	1	14	I	LNA and Log Detector block enable and disable pin. AFE_En = High for AFE enable. Floating this pin keeps both blocks enabled as well.
AGND	13	10	Р	Analog ground for LNA and Log detector block
Buffer	10	7	0	Noninverting buffered output. V _{Buffer} = V _{Log_Out} × 2.
DGND	2	15	Р	Digital ground for Freq_Out pin
Freq_Out	8	5	0	This pin toggles at the same signal frequency applied at the Log_In.
Freq_Supply	7	4	Р	Power supply for Freq_Out function. Float this pin if the frequency-detection feature is not required.
Inv_Buffer	9	6	0	Inverted buffered output. V _{Inv_Buffer} = V _{Log_Out} × –2.
LNA_En	3	16	1	Low-noise amplifier enable and disable. LNA_En = High for LNA enable. Floating this pin keeps the LNA enabled as well.
LNA_In	16	13	I	Low-noise amplifier input
LNA_Out	14	11	0	Low-noise amplifier output
Log_Inm	11	8	I	Inverting input of Log Detector block. Connect an appropriate capacitor to ground when used in a single-ended input. Refer to Section 7.3.2.
Log_Inp	12	9	I	Noninverting input of Log Detector block
Log_Out	5	2	0	Unbuffered output of Log Detector block. Connect an appropriate resistor R_F (to set the input to output slope) and capacitor C_F (to set the response time).
Offset_Cap	15	12	I	Connect a recommended capacitor from this pin to ground. This capacitor sets the pole of the internal offset correction loop. Refer to Section 7.3.1 for the recommended capacitor.
Ref_Res	6	3	I	Connect a 1% $56k\Omega$ resistor to this pin. Float this pin if the default relaxed slope accuracy is acceptable.
VCC	4	1	Р	Supply
Thermal Pad	_	Thermal Pad	Р	Thermal pad. Electrically isolated from the device. Connect to a heat spreading plane, typically ground.

⁽¹⁾ I = input, O = output, I/O = input or output, G = ground, P = power.



5 Specifications

5.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
VCC	Supply voltage and Freq_Supply		5.5	V
	AFE_En and LNA_En	GND	VCC	V
LNA_In	LNA input voltage		±1	V_P
Log_In	Single ended input voltage (Log_Inp and Log_Inm)	(VCC×	0.17) + 0.9	V_P
I _I	Continuous input current for all pins ⁽²⁾		±10	mA
	Continuous power dissipation	See Thermal Informa	tion	
T _J	Maximum junction temperature		150	°C
T _{stg}	Storage temperature	-65	150	°C

⁽¹⁾ Operation outside the Absolute Maximum Ratings can cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

5.2 ESD Ratings

			VALUE	UNIT
V	Electrostatic	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±1000	V
V _(ESD)	discharge	Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±500	V

⁽¹⁾ JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	3		5.25	V
T _A	Ambient operating temperature	-40	25	125	°C
Ref_Res	Recommended reference resistor to ground		56		kΩ

5.4 Thermal Information

			LOG300		
	THERMAL METRIC(1)	D (SOIC)	VQFN (RGT)	UNIT	
		16 PINS	16 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	81.1	48.2	°C/W	
R _{0JC(top)}	Junction-to-case (top) thermal resistance	43.3	56.0	°C/W	
$R_{\theta JB}$	Junction-to-board thermal resistance	43.5	23.4	°C/W	
Ψ_{JT}	Junction-to-top characterization parameter	7.7	1.6	°C/W	
ΨЈВ	Junction-to-board characterization parameter	43.1	23.4	°C/W	
R _{0JC(bottom)}	Junction-to-case (bottom) thermal resistance	N/A	8.2	°C/W	

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

Product Folder Links: LOG300

⁽²⁾ Input pins are diode-clamped to the power-supply rails. Current limit the input signals, which can swing more than 0.5V beyond the supply rails to 10mA or less.

⁽²⁾ JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.5 Electrical Characteristics Low Noise Amplifier (LNA)

at T_A = 25°C, VCC = 3.3V to 5V, LNA_Out = 1k Ω to AGND, R_{SOURCE} = 50 Ω , and input ac coupling capacitor (C_{IN}) = 10nF to AGND (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DC PERF	FORMANCE					
G _{LNA}	Internal gain			11		V/V
	Internal gain error	T _A = -40°C to +125°C		±0.8	±1	%
AC PERF	FORMANCE				-	
SSBW	Small-signal bandwidth	LNA_Out = 20mV _{PP}		39		MHz
LSBW	Large-signal bandwidth			36		MHz
SR	Slew rate	2V step at LNA_Out		200		V/µs
	Total input referred noise	f > 100kHz, includes gain and bias resistors		2.6		nV/√Hz
	Overdrive recovery time	2 × output overdrive		1		μs
	Capacitive drive ⁽¹⁾	< 3dB of peaking		∞		nF
INPUT						
.,		VCC = 5V			200	.,
V_{LNA_In}	Linear input voltage	VCC = 3.3V			140	mV_P
	Internal bias voltage	At LNA_In, T _A = -40°C to +125°C		VCC × 0.044		mV
	Input impedance of LNA			1.7 1.8		kΩ pF
OUTPUT					-	
	Output bias point of LNA	LNA_In = open		V _{BIAS} × 11		V
	Output impedance of LNA		0.850	1	1.150	kΩ
POWER	SUPPLY					
	Out a sent an anotin a summant			2	2.7	А
	Quiescent operating current	T _A = -40°C to +125°C			3	mA
POWER	DOWN					
	LNA enable voltage threshold	Floating = enable	VCC - 1.2			٧
	LNA disable voltage threshold				GND + 0.6	V
	Turn-on time	Time from disable to enable		36	60	μs
	Turn off time	Time from enable to disable		130	200	ns

⁽¹⁾ Infinite capacitive drive possible due to presence of $1k\Omega$ of isolation resistor



5.6 Electrical Characteristics Log Detector

at T_A = 25°C, VCC = 3.3V to 5V, C_F = 1nF, R_F = 43k Ω (slope = 43mV/dB) for VCC = 5V and R_F = 30k Ω for VCC = 3.3V, Ref_resistor = 1% 56k Ω , 10nF capacitor to AGND on Log_inp and Log_inm (unless otherwise noted)⁽⁴⁾

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
AC PEF	RFORMANCE						
		£ = 40411=			±0.6	±1	
	(3)	f = 1MHz	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			±1.1	10
LCE	Log conformance error ⁽³⁾	5 40MU-			±2	±2.5	- dB
		f = 40MHz	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			±2.9	
DR	Dynamic range ⁽³⁾	LCE = ±1dB, f = 1MHz		96	98		dB
	Log Detector slope ⁽¹⁾			R _F	value in kΩ ⁽²⁾		mV/dB
		Ref Res = 56kΩ of 1%			±1	±6	
	Log Detector	accuracy, f = 1MHz	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$,	±6.8	٥,
	slope variation ⁽³⁾	D (D () ()			±4.5		%
		Ref_Res = open, f = 1MHz	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$		±5.6		
INPUT							
				20µ		1.2	
	I	VCC = 3.3V, LCE = ±2dB, f = 20MHz	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	24µ		1	
	To all the section of the sec		$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	26µ		0.8	,,
V_{Log_In}	Typical input voltage	I - ZUIVITZ		20µ		1.6	V _P
			$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	22µ		1.6	1
			$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$	32µ		1.6	
	Differential input voltage	(Log_Inp) – (Log_Inm), T _A =	-40°C to +125°C		,	±1.6	V
	Internal bias voltage	Log_Inp and Log_Inm			1.7		V
	Input impedance	for Log_Inp and Log_Inm			1.7 10		kΩ pF
LOG_O	UT						
		C _F = 220pF			20		
	Log_Out rise time	C _F = 1nF			95		μs
		C _F = 220pF			27		
	Log_Out fall time	C _F = 1nF			100		μs
	Output overdrive recovery	C _F = 220pF			250		μs
	(5) (2)			83	155	205	,.
	Minimum output voltage ⁽⁵⁾ (3)	Log_Inp = 10nF to AGND	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			340	mV
	Maximum output voltage	T _A = -40°C to +125°C		VCC- 0.3			V

Submit Document Feedback



5.6 Electrical Characteristics Log Detector (continued)

at T_A = 25°C, VCC = 3.3V to 5V, C_F = 1nF, R_F = 43k Ω (slope = 43mV/dB) for VCC = 5V and R_F = 30k Ω for VCC = 3.3V, Ref resistor = 1% 56k Ω , 10nF capacitor to AGND on Log inp and Log inm (unless otherwise noted)⁽⁴⁾

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
BUFFE	ER OUTPUT						
	Gain	V _{Buffer} /V _{Log_Out}			+2		V/V
	Output voltage equation			L	2 × .og_Out		V
	Output-referred offset					30	mV
	Output voltage	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		GND + 0.1		VCC- 0.1	V
	Rise-and-fall response time ⁽²⁾	C _{Load} R _{Load} = 100pF 1	10kΩ		1.5		μs
	Short-circuit current	Source-and-sink current		20			mA
Z _{OUT}	Output impedance				5.3		Ω
INV_B	UFFER OUTPUT						
	Gain	V _{Inv_Buffer} /V _{Log_Out}			-2		V/V
	Output voltage equation			L	VCC - (2 × og_Out)		V
	Output voltage	T _A = -40°C to +125°C		GND + 0.1	·- ·	VCC - 0.1	V
	Rise-and-fall response time ⁽²⁾	C _{Load} R _{Load} = 100pF 1	10kΩ		1.5		μs
	Output-referred offset					32	mV
	Short-circuit current	Source-and-sink current		20			mA
	Output impedance				6.3		Ω
FREQ	UENCY DETECT OUTPUT			I			
	Frequency detect block	cv detect block Log_Inp signal of f < 2MHz	łz	250µ		1.6	
	typical input sensitivity	Log_Inp signal of f < 20M	lHz	1.7m		1.6	V_P
	Freq_Out swing			DGND		Freq_Supply	V
POWE	R SUPPLY	·					
		From Cumply - Onco			4.1	4.6	
	Quiescent current	Freq_Supply = Open	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			5.9	mA
		Freq_Supply = VCC	•			0.37	

- (1) Log Detector slope reduces with increased input signal frequency, refer to Typical Characteristics
- (2) Refer to Parameter Measurement Information for definition of R_F
- (3) Charecterized through 32 units
- (4) The symbol f stands for a short burst of sinewave of a frequency, f, applied at the Log_Inp pin. This definition holds through across the data sheet.
- (5) Minimum output voltage is the lowest voltage Log_Out settles to, when inputs are shorted to AGND pin via a high value capacitor with no signal being applied.



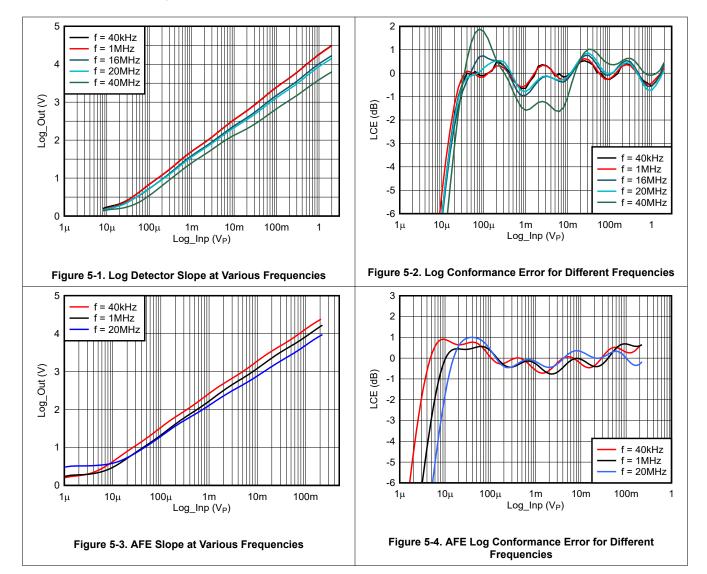
5.7 Electrical Characteristics LNA + Log Detector (AFE)

at T_A = 25°C, VCC = 5V, C_F = 1nF and R_F = 43k Ω (slope = 43mV/dB for f = 1MHz), Ref_resistor = 1% 56k Ω , with 2nd-order external band-pass filter (BPF) of gain = -7dB, and R_{SOURCE} = 50 Ω (unless otherwise noted)

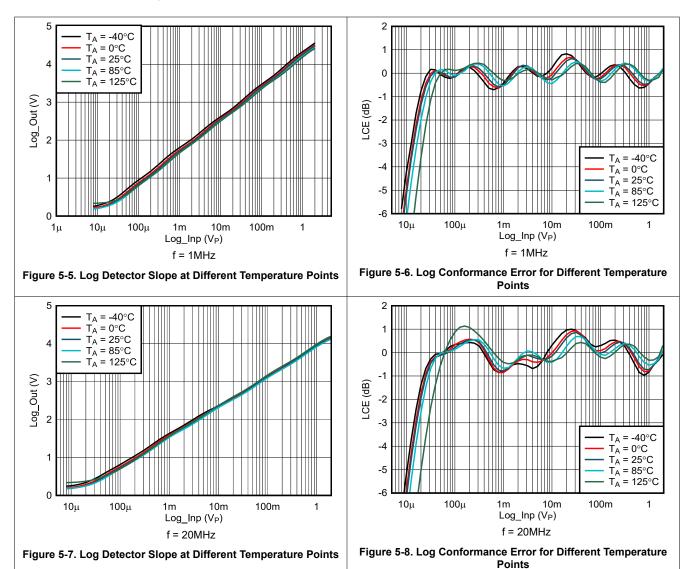
	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
AFE A	C PERFORMANCE						
. 05		5 48411-			±0.6	±1.2	-ID
LCE	Log conformance error	f = 1MHz	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$,	±1.3	dB
DR	Dynamic range	For LCE = ±1.2dB, f = 1MHz			91		dB
		Ref_Res = open			±4.5		
	Log Detector slope variation	Ref_Res = 56kΩ of 1% accura	ıcy		±1	±7	%
		Ref_Res = 56kΩ of 1%	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			±7	
AFE IN	IPUT	1					
		LOF = 11dD f = 1MU=		6µ		200m	
AFE	Typical input valtage	LCE = ±1dB, f = 1MHz	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$	8µ		200m	\ /
input	Typical input voltage	LCE = ±1dB, f = 20MHz		9μ		200m	V _P
		LCE - ±10B, I - 20MINZ	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	10µ		200m	
	Output ring time	BPF = $180kHz$, $C_F = 350pF$ BPF = $1MHz$, $C_F = 500pF$			35		116
	Output rise time				50		μs
	Output fall time	BPF = 180kHz, C _F = 350pF			65		
	Output fall time	BPF = 1MHz, C _F = 500pF			45		μs
LOG_C	DUT						
	Minimum output voltage	I NIA In - 10nE to ACND			290	335	mV
	Minimum output voltage	LNA_In = 10nF to AGND	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			436	IIIV
POWE	R SUPPLY						
	Quiescent current	Total AFE, LNA_Out = open,			6	7.2	mA
	Quiescent current	Freq_Supply = open	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			8.3	ША
POWE	R DOWN						
	Disabled current	Total AFE	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			130	μA
AFE	AFE enable voltage threshold	Floating = enable		VCC- 1.2			V
En	AFE disable voltage threshold					AGND + 0.6	V

Submit Document Feedback

5.8 Typical Characteristics: VCC = 5V







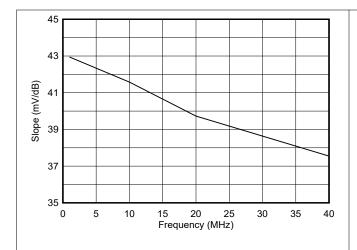


Figure 5-9. Log Detector Slope Variation with Input Signal Frequency

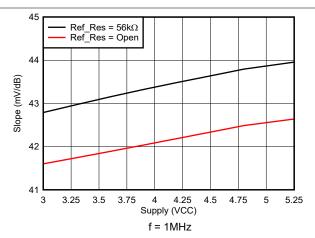


Figure 5-10. Log Detector Slope Variation vs Supply

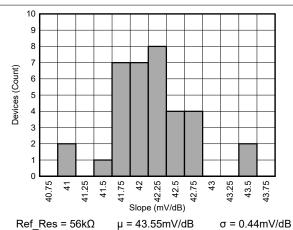


Figure 5-11. Log Detector Slope Histogram with Ref_Res

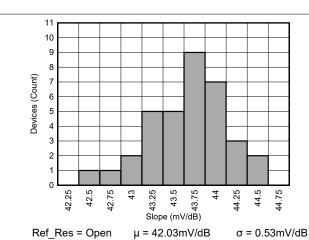
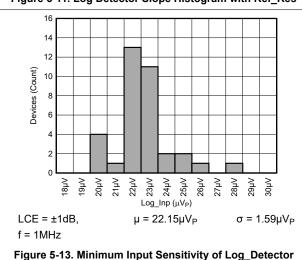


Figure 5-12. Log Detector Slope Histogram without Ref_Res



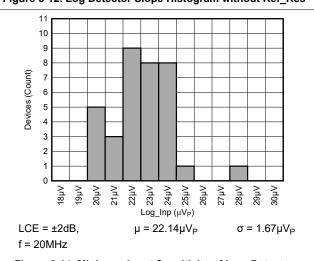
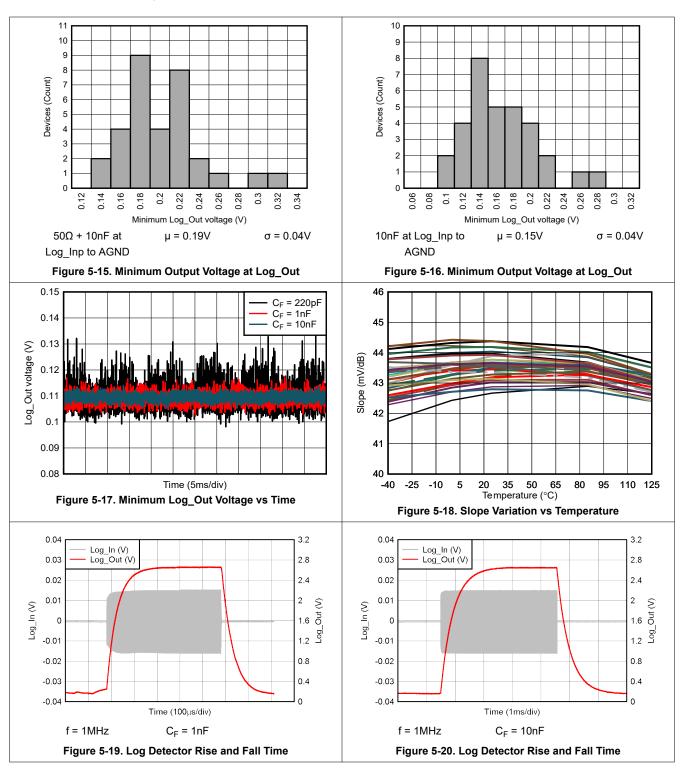
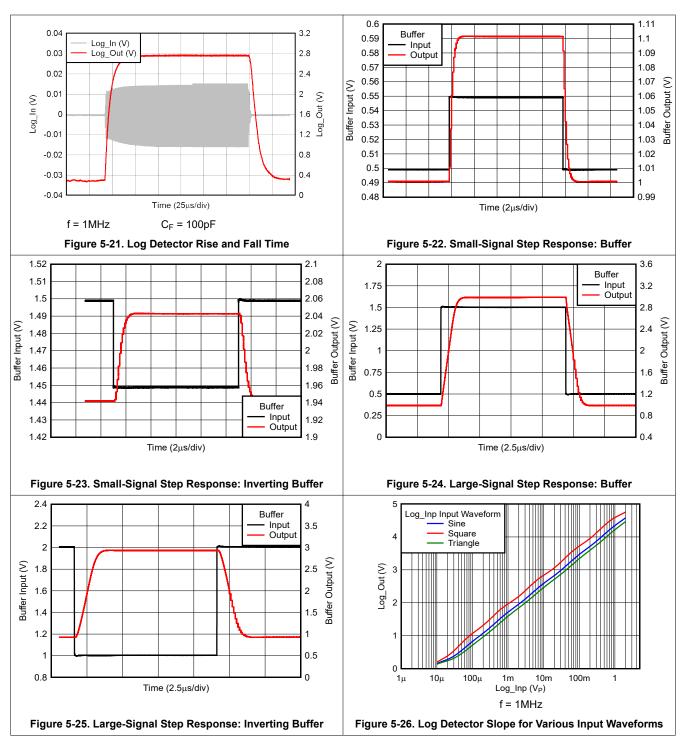


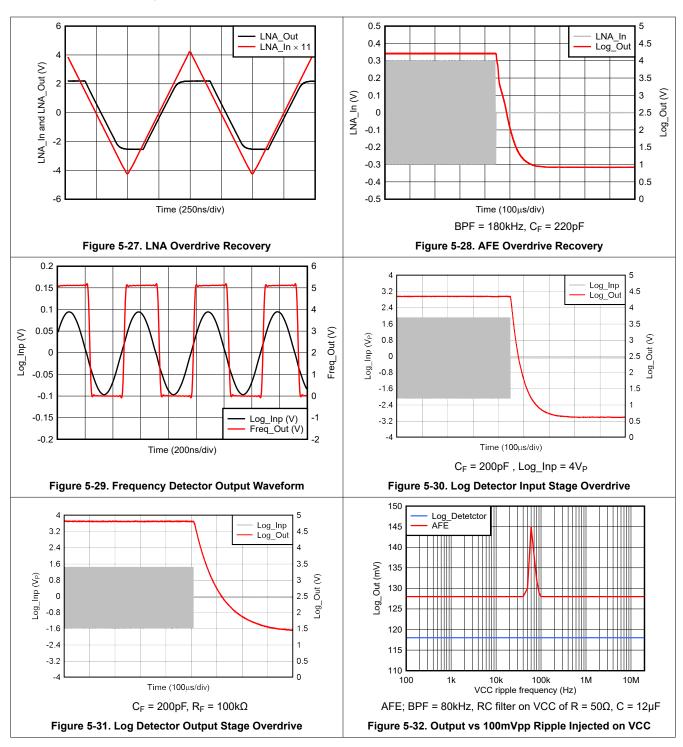
Figure 5-14. Minimum Input Sensitivity of Log_Detector



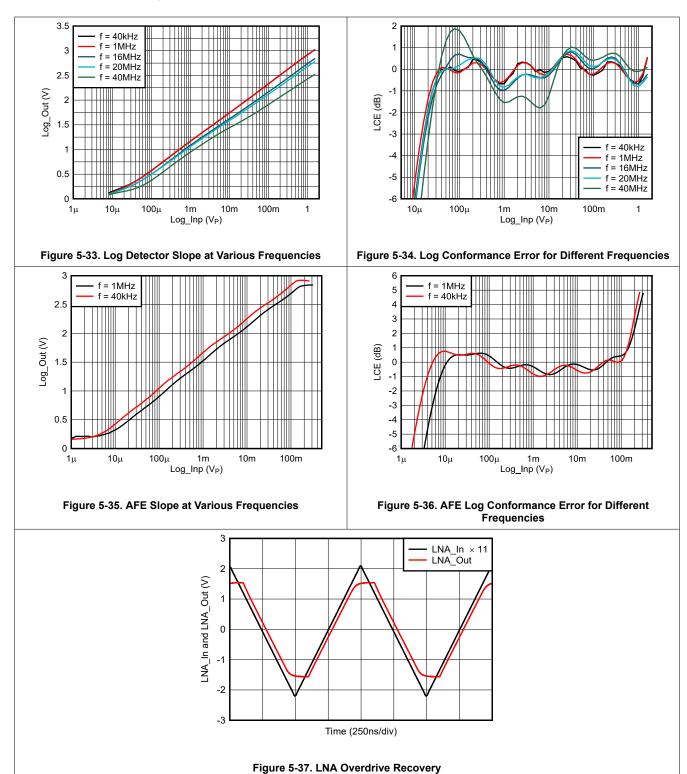








5.9 Typical Characteristics: VCC = 3.3V





6 Parameter Measurement Information

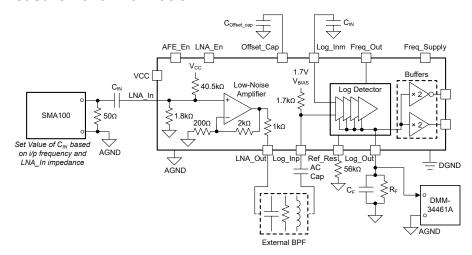


Figure 6-1. LOG300 Slope Characterization

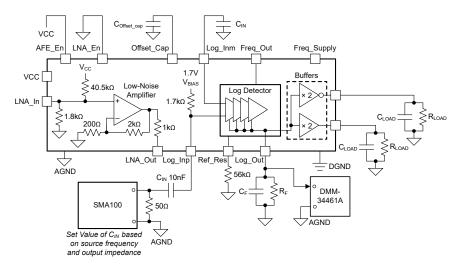


Figure 6-2. Log Detector Slope Characterization

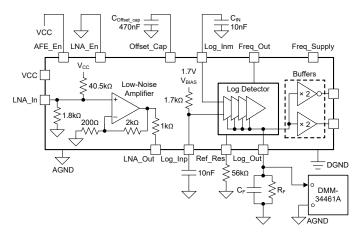


Figure 6-3. Log Detector Minimum Output Voltage Measurement

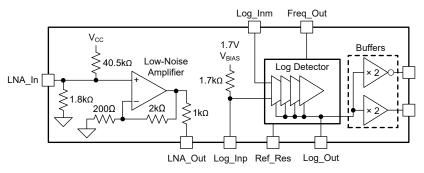
Submit Document Feedback

7 Detailed Description

7.1 Overview

The LOG300 is a highly sensitive analog front-end system for power measurements of up to 40MHz signals with a typical dynamic range of 98dB. The LOG300 is intended for use in a wide variety of applications like ultrasonic Rx signal chains, amplitude demodulation, signal power measurement, grid monitoring and so on. The LOG300 provides an analog envelope of an amplitude proportional to the log of the input signal. This behavior provides the application circuit precise input signal amplitude measurement without the need of high-speed signal acquisition components. The integrated frequency-detect feature enables zero-crossing and frequency measuring capability of the incoming signal.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Offset Correction Loop (OCL)

The LOG300 comes with an internal offset correction loop (OCL) designed to correct for any small offset voltage errors due to external factors or due to the input gain blocks mismatch. The LOG300 internal gain blocks offer very high gain; therefore, any small error at the input is sufficient to saturate the log output.

The Offset_Cap (see Section 6) sets the time constant of the offset correction loop. Set the value of the OCL pole to less than the incoming signal frequency so that the OCL does not respond to the incoming signal. Use the following formula to calculate the value of Offset_Cap based on the frequency of the incoming signal.

$$C_{Offset_Cap}(nF) \ge \frac{6000}{Frequency\ of\ input\ signal\ (kHz)}$$
 (1)

Where

- Offset capacitor must never be less than 1nF. If the formula yields a value of C_{Offset_Cap} less than 1nF, use 1nF.
- Using a value of C_{Offset_Cap} greater than the calculated value using above equation is acceptable since the OCL loop is set to a lower frequency.

7.3.2 Single and Differential Input

The Log Detector block of the LOG300 supports both single-ended and differential input signals. Irrespective of the type of input signal, the impedances of the Log_Inp and Log_Inm pins to AGND have to be matched.

The requirement for impedance matching arises from the fact that any supply noise or externally coupled noise passes through these impedances and the generated voltage. If the impedances are mismatched at the two inputs a differential voltage is seen by the Log Detector block thereby increasing the minimum output voltage at the Log_Out pin.

Achieving impedance matching for differential inputs can be straightforward. However for single-ended inputs, impedance matching can be quite complex. If board space is not limited TI recommends to copy the input structure at the Log_Inp pin as is on to the Log_Inm input. Please take note of the default internal output impedance of the LNA of $1k\Omega$ when copying the structure to the Log_Inm pin.

If the above recommendation is not possible, match the impedances between the two pins at the frequency with the highest probability of noise coupling. For example if the VCC power is being derived by a DC/DC converter switching at a maximum frequency of 500kHz, using option 1 gives the best impedance matching between Log_Inp and Log_Inm. If the VCC ripple is at 100kHz then both option 1 and option 2 result in the same rejection response.

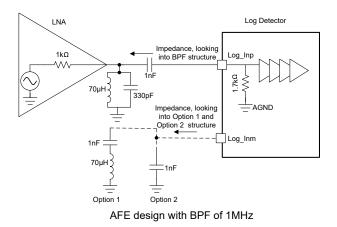


Figure 7-1. Impedance Structure at Log_Inp and Log_Inm

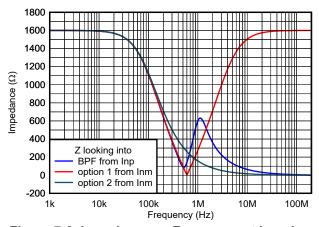


Figure 7-2. Impedance vs Frequency at Log_Inp and Log_Inm

Submit Document Feedback

7.3.3 Input Frequency Detect

The Log_Out pin creates an envelope proportional to the incoming signal; therefore, the frequency and phase information of the input signal is lost. The frequency detect feature enables the LOG300 to recover this frequency information. The frequency detect pin toggles at the same frequency as the input, and can therefore be used to calculate the input signal frequency or the input signal zero crossing points.

The internal circuit consists of a comparator with one of the inputs connected to the pin Log_In bias voltage and the other input of the comparator connected to the last stage of the Log Detector gain block (see Figure 7-3). Log In is ac coupled; therefore, the incoming signal is biased to the internal bias voltage.

The comparator compares the gained Log_In (both single-ended and differential) signal biased at the internal bias voltage with the DC internal bias voltage, thereby toggling at every instance of a zero crossing. If the incoming signal is not a symmetric waveform or consists of multiple frequency content, the frequency detect feature compares the zero crossings of the incoming signal.

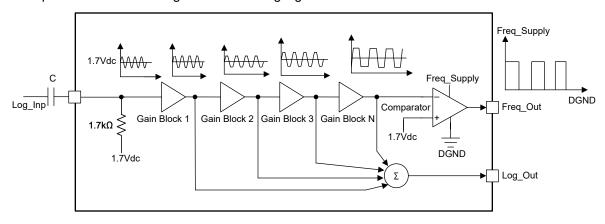


Figure 7-3. Internal Block Diagram for Frequency Detect

7.4 Device Functional Modes

The LOG300 offers three functional modes:

- AFE Disabled
 - In this mode, the complete AFE (LOG300) is disabled and consumes only about 100μA.
- LNA Disabled
 - In this mode, the LNA is disabled, while the Log Detector block is still operational. See Section 5.6 for detailed parameters in this mode.
 - Typically, this mode is used when the input sensitivity required is relaxed and the application prioritizes a lower quiescent current. Disabling the LNA helps save 2mA of quiescent current originally consumed by the LNA.
- · Normal operating mode
 - In this mode, all blocks of the LOG300 are operational. See Section 5.7 for detailed parameters such as power consumption, acceptable supply, and input output range.
 - This mode can be entered by floating the LNA En and AFE En pins or by tying them to VCC.

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The LOG300 is a good fit for multiple applications involving ultrasound receive signal measurement, power, and energy measurements. The wide dynamic range and high input sensitivity makes the LOG300 an excellent option for applications such as the example in Section 8.2.1 involving measurement of low amplitude signals without the need of expensive, high-bandwidth, low-noise components.

8.2 Typical Application

8.2.1 Ultrasonic Distance Measurement

This design example demonstrates the circuit calculations and discrete component selection around the LOG300 to achieve a highly sensitive receive signal chain for a typical ultrasonic distance based measurement sensor.

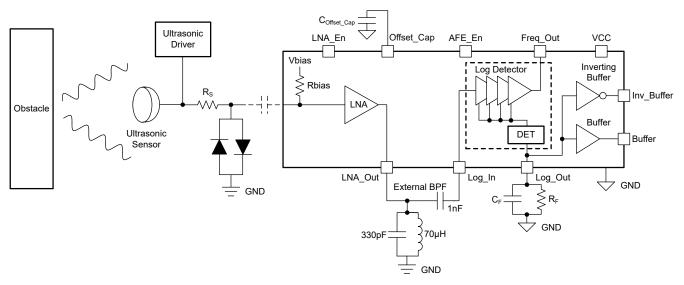


Figure 8-1. Ultrasonic Distance Sensor

8.2.1.1 Design Requirements

Table 8-1. Design Parameters

PARAMETER	VALUE
Supply (VCC)	5V
Minimum input signal measuring capability	6μV _P
Maximum input signal measuring capability: Linear	200mV _P
Maximum input signal handling capability (V _{max})	100V _P
Frequency of Tx and Rx signal	1MHz
Log_Out; Output range	0.5V to 4.5V

Submit Document Feedback

8.2.1.2 Detailed Design Procedure

The LOG300 supports a 5V VCC. Add a 10Ω and 10μ F || 10μ F close to the VCC pin to provide sufficient decoupling and immunity from external noise. This supply filter has a pole of 1.59kHz that is sufficiently less than the frequency of interest, which is 1MHz.

The absolute maximum voltage rating of pin LNA_In is $\pm 1V$. Add a back-to-back diode along with a series resistor (R_S) at the input of the LNA (see also Figure 8-1). The back-to-back diode protects the LNA_In pin from being exposed to any high voltages, especially during the transmit operation. Choose the series resistance value in accordance to the maximum power rating (P_{MAX}) of the back-to-back diode. The added series resistor contributes to the input noise and deteriorates the minimum input sensitivity.

$$R_{s} = \frac{(0.7V \times (V_{max} - 0.7V))}{P_{max}}$$
 (2)

The maximum expected output voltage of the LNA with a back-to-back diode placed at the input is:

$$11V/V \times 0.7V_{P} = 7.7V_{P} \tag{3}$$

Since the LNA is only powered from a 5V supply; the maximum output is only 2.5V_P.

The maximum input for the Log_Inp pin is $1.7V_P$ for 5VCC (see also Section 5.1); therefore, add a band-pass filter (BPF) of appropriate attenuation in the pass-band region so that the detector block absolute maximum voltage rating is not violated. In this particular case, ensure that the BPF has an attenuation of at least -3.3dB. A BPF of -4.3dB is shown in Figure 8-1.

Choose an Offset Cap value based on Section 7.3.1.

Choose the value of C_F based on the required rise time of the Log_Out pin voltage (V_{Log_Out}). A lower-value C_F improves the rise time at the cost of higher ripple on the output envelope. For reference plots see also Section 5.8. Connect an oscilloscope at the Log_Out pin, triggered during the receive burst operation, to find the correct balance between the required rise time and the acceptable ripple.

The R_F resistor decides the input-to-output slope. The value of R_F in $k\Omega$ equals the input-to-output slope in mV/dB. In this example, calculate R_F using the below set of equations:

Slope
$$mV/dB = R_F k\Omega = \frac{(Saturated\ output\ voltage\ -\ Minimum\ output\ voltage)}{(20\ x\ log\ (Maximum\ LNA_In\ -\ Minimum\ LNA_In))}$$
 (4)

Slope mV/dB =
$$\frac{(4.5V - 0.5V)}{(20 \times \log{(200mV - 6\mu V)})}$$
 (5)

Slope
$$(mV/dB) = 44mV/dB$$
 hence use $R_F k\Omega = 44k\Omega$ (6)

Note

The maximum and minimum Log_Out values have been relaxed to design for the output to operate well within the linear range.

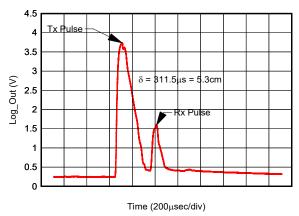
The voltage measured at Log_Out can be traced back to calculate the input amplitude using the below equation:

$$Log_{-}Out_{A} = Slope x \left(\frac{Log_{-}In_{A}}{Log_{-}In_{B}}\right) + Log_{-}Out_{B}$$
(7)

$$Log_{-}In_{A} = \left(\frac{Log_{-}Out_{A} - Log_{-}Out_{B}}{Slope \ x \ Log_{-}In_{B}}\right)$$
(8)

Where : A stands for values of Log_Out and Log_In at the required measurement point and B stands for Log_Out and Log_In values at a known input value measured during factory calibration or production.

8.2.1.3 Application Curves



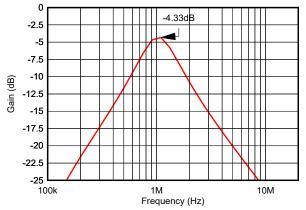


Figure 8-2. Log_Out Response for Ultrasonic Distance Measurement

Figure 8-3. Band-Pass Filter Frequency Response

8.3 Power Supply Recommendations

The LOG300 contains two supply pins. The analog power supply pin (VCC) and the frequency detect block supply pin (Freq_Supply). Both pins can be biased at any voltage between 3V to 5.25V with respect to the AGND. While both these pins are connected to different circuitry internally, TI recommends to connect both of these pins to the same potential. Provide separate decoupling capacitors, resistors, and ferrite beads to these supply pins (see Section 8.4.2) to maintain sufficient immunity against cross coupling.

The LOG300 is sensitive to the noise coupling through the supply pins. Use a low-pass filter on the supply line with a cutoff frequency less than the incoming frequency signal.

For example if the incoming signal is 100kHz, and the band-pass filter has been tuned to achieve a center frequency of 100kHz, design a RC filter on the supply with a cut off frequency of at least 10kHz. For a higher signal frequency the RC values start diminishing to smaller values and hence the cut off frequency can be parked to any appropriate value.

An external band-pass filter if used between the LNA and the LOG detector block, along with a low-pass filter on the supply pins provides enough power-supply rejection to keep Log. Out unaffected.

Submit Document Feedback

8.4 Layout

8.4.1 Layout Guidelines

Follow these instructions to improve the performance and noise immunity of the LOG300:

- Provide a star connection style supply for Freq_supply and VCC. This connection enables better noise immunity and decoupling.
- Design Log_Inp, Log_Inm and LNA_In traces with guard traces to improve immunity against noise pickup.
 Use shielding when possible to improve radiated noise immunity.
- Place small capacitors on the AFE and LNA enable pins to allow high-frequency noise to be grounded before
 entering into the device.
- As per Section 7.3.2 the impedance seen from Log_Inp and Log_Inm to the external circuit must be the same. The trace length to Log_Inp and Log_Inm must be kept similar to keep impedance matched.
- Keep minimal capacitance at the Freq_Out pin either by placing the load circuit close to the pin or by removing the analog ground plane under the output trace or both.
- Dedicate one layer of the PCB for a solid analog ground pour to terminate all the capacitors used across the pins using sufficient vias.

8.4.2 Layout Example

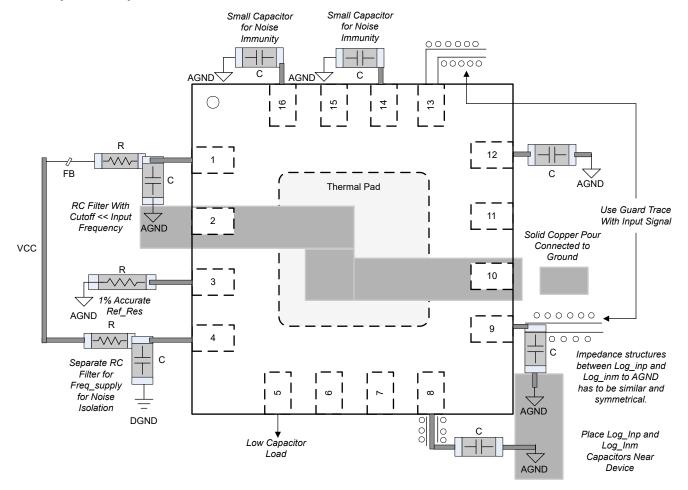


Figure 8-4. Layout Example



9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

9.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

TI E2E[™] support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

9.4 Trademarks

TI E2E[™] is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (September 2024) to Revision A (October 2024)

Page

Changed document status from advanced information (preview) to production data (active)......1

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Copyright © 2024 Texas Instruments Incorporated
Product Folder Links: *LOG300*

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2024, Texas Instruments Incorporated